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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

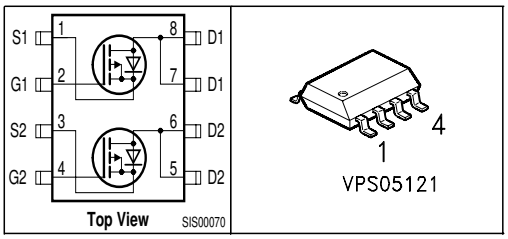
OptiMOS™-P Power-Transistor

Feature

- Dual P-Channel
- Enhancement mode
- Logic Level
- 150°C operating temperature
- Avalanche rated
- d*v*/d*t* rated

Product Summary

V_{DS}	-30	V
$R_{DS(on)}$	21	mΩ
I_D	-8.2	A



Type	Package
BSO303P	P-SO 8

Maximum Ratings,at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current T_A=25°C T_A=70°C	I_D	 -8.2 -6.6	A
Pulsed drain current T_A=25°C	$I_{D\ puls}$	-32.4	
Avalanche energy, single pulse I_D=-8.2 A , V_{DD}=-25V, R_{GS}=25Ω	E_{AS}	97	mJ
Reverse diode d*v*/d*t* I_S=-8.2A, V_{DS}=-24V, d*i*/d*t*=200A/µs, T_{jmax}=150°C	d*v*/d*t*	-6	kV/µs
Gate source voltage	V_{GS}	±20	V
Power dissipation T_A=25°C	P_{tot}	2	W
Operating and storage temperature	T_j , T_{stg}	-55... +150	°C
IEC climatic category; DIN IEC 68-1		55/150/56	

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - soldering point	R_{thJS}	-	-	50	K/W
SMD version, device on PCB:	R_{thJA}				
@ min. footprint, t < 10s		-	-	110	
@ 6 cm^2 cooling area [1)]		-	-	62.5	

Electrical Characteristics, at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain-source breakdown voltage V_{GS}=0, I_D=-250µA	$V_{(BR)DSS}$	-30	-	-	V
Gate threshold voltage, V_{GS} = V_{DS} I_D=-100µA	$V_{GS(th)}$	-1	-1.5	-2	
Zero gate voltage drain current	I_{DSS}				µA
V_{DS}=-30V, V_{GS}=0, T_j=25°C		-	-0.1	-1	
V_{DS}=-30V, V_{GS}=0, T_j=150°C		-	-10	-100	
Gate-source leakage current V_{GS}=-20V, V_{DS}=0	I_{GSS}	-	-10	-100	nA
Drain-source on-state resistance V_{GS}=-4.5V, I_D=-6.6A	$R_{DS(on)}$	-	26	32	mΩ
Drain-source on-state resistance V_{GS}=-10V, I_D=-8.2A	$R_{DS(on)}$	-	18	21	

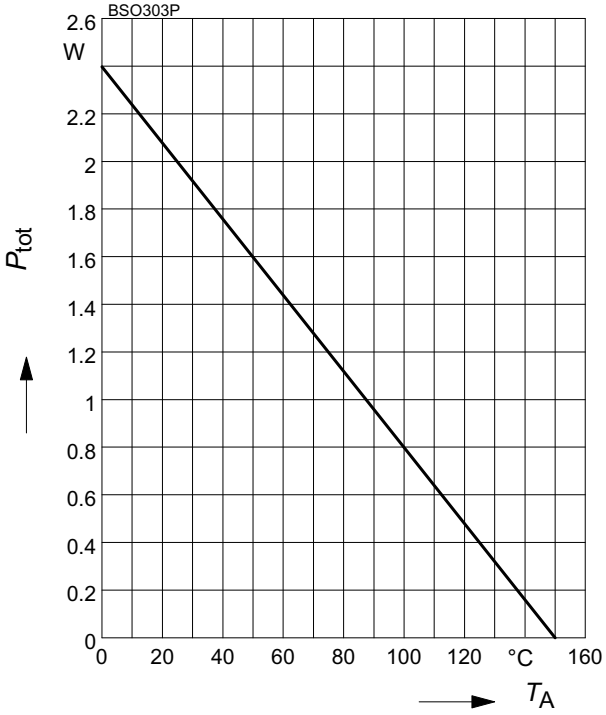
[1]Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical without blown air; t≤10 sec.

Electrical Characteristics, at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic Characteristics						
Transconductance	g_{fs}	$\lvert V_{DS}\rvert \geq 2 * \lvert I_D\rvert * R_{DS(on)max}$, I_D=-6.6A	11	22	-	S
Input capacitance	C_{iss}	V_{GS}=0, V_{DS}=-25V, f=1MHz	-	1761	-	pF
Output capacitance	C_{oss}		-	495	-	
Reverse transfer capacitance	C_{rss}		-	410	-	
Turn-on delay time	$t_{d(on)}$	V_{DD}=-15V, V_{GS}=-10V, I_D=-1A, R_G=6Ω	-	10.6	15.9	ns
Rise time	t_r		-	12.9	19.3	
Turn-off delay time	$t_{d(off)}$		-	55.4	83.1	
Fall time	t_f		-	39.3	59	
Gate Charge Characteristics						
Gate to source charge	Q_{gs}	V_{DD}=-24V, I_D=-8.2A	-	-4.25	-6.4	nC
Gate to drain charge	Q_{gd}		-	-15.2	-23	
Gate charge total	Q_g	V_{DD}=-24V, I_D=-8.2A, V_{GS}=0 to -10V	-	-48.3	-72.5	
Gate plateau voltage	$V_{(plateau)}$	V_{DD}=-24V, I_D=-8.2A	-	-2.4	-	V
Reverse Diode						
Inverse diode continuous forward current	I_S	T_A=25°C	-	-	-2.2	A
Inverse diode direct current, pulsed	I_{SM}		-	-	-32.4	
Inverse diode forward voltage	V_{SD}	V_{GS}=0, $\lvert I_F\rvert = \lvert I_D\rvert$	-	-0.88	-1.32	
Reverse recovery time	t_{rr}	V_R=-15V, $\lvert I_F\rvert = \lvert I_D\rvert$, di_F/dt=100A/µs	-	24.4	36.6	ns
Reverse recovery charge	Q_{rr}		-	12.8	19.2	nC

1 Power dissipation

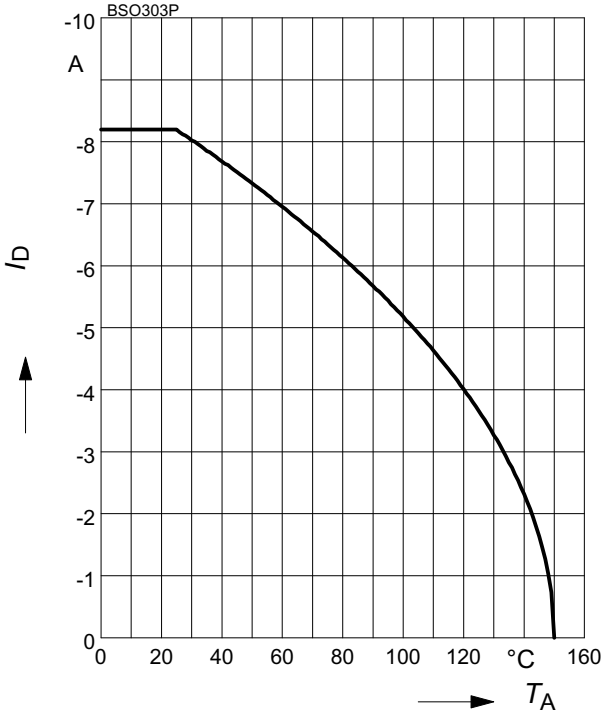
$P_{tot} = f(T_A)$



2 Drain current

$I_D = f(T_A)$

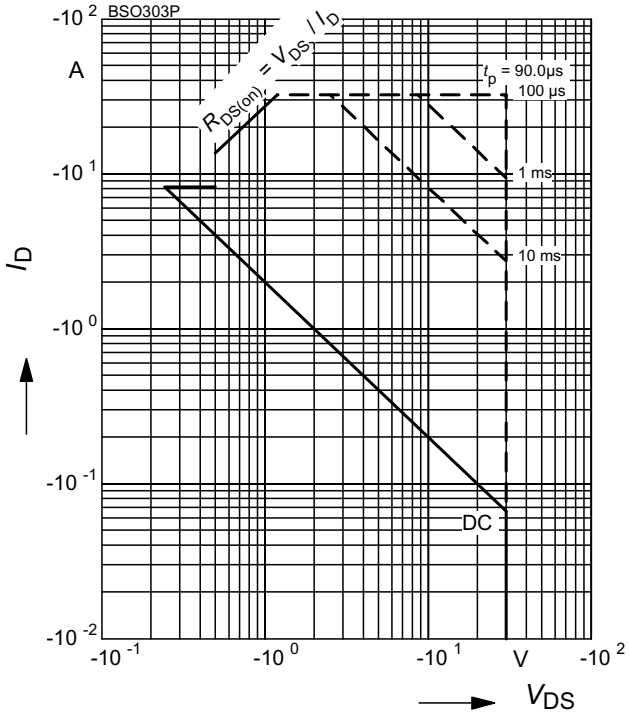
parameter: $|V_{GS}| \geq 10$ V



3 Safe operating area

$I_D = f(V_{DS})$

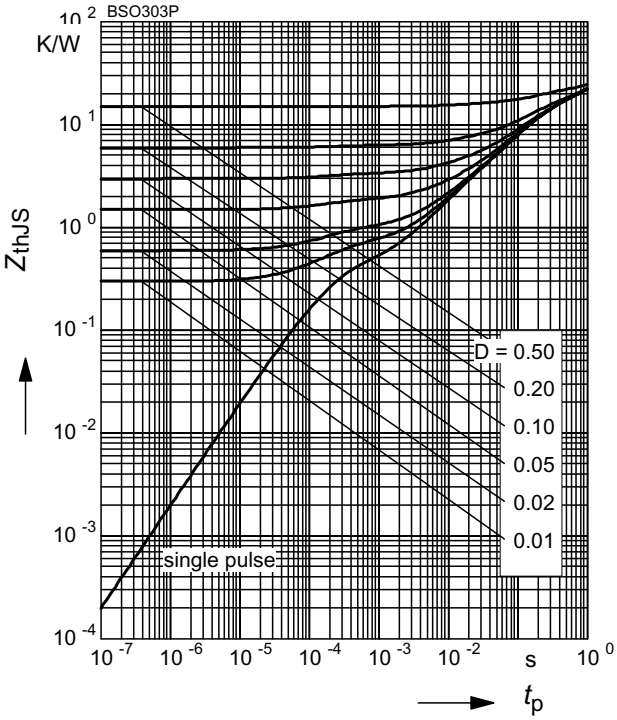
parameter : $D = 0$, $T_A = 25$ °C



4 Transient thermal impedance

$Z_{thJS} = f(t_p)$

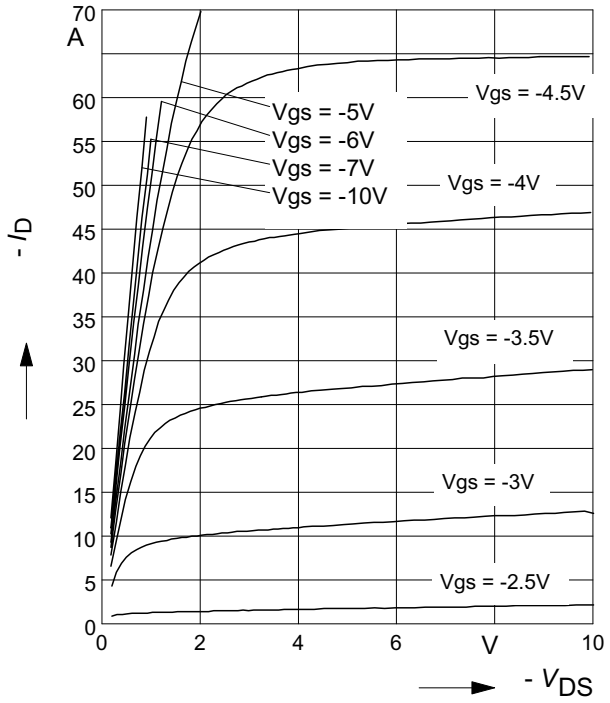
parameter : $D = t_p/T$



5 Typ. output characteristic

$I_D = f(V_{DS})$; T_j=25°C

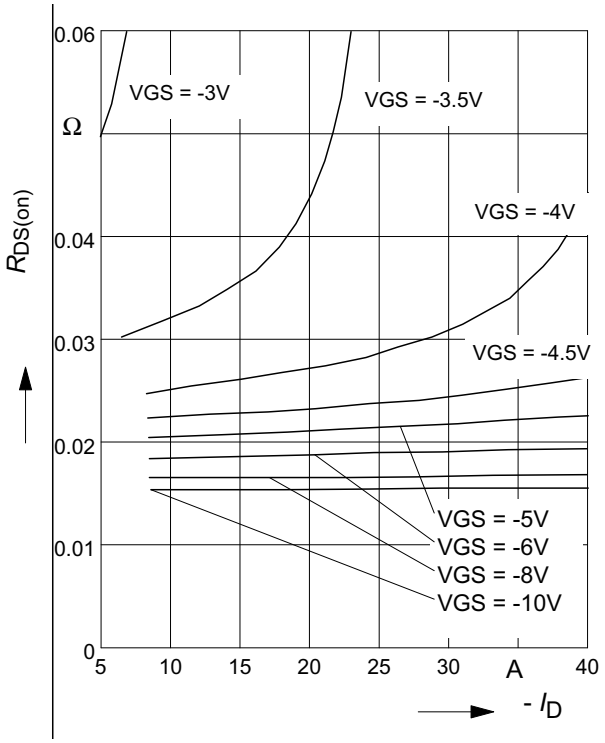
parameter: t_p = 80 µs



6 Typ. drain-source on resistance

$R_{DS(on)} = f(I_D)$

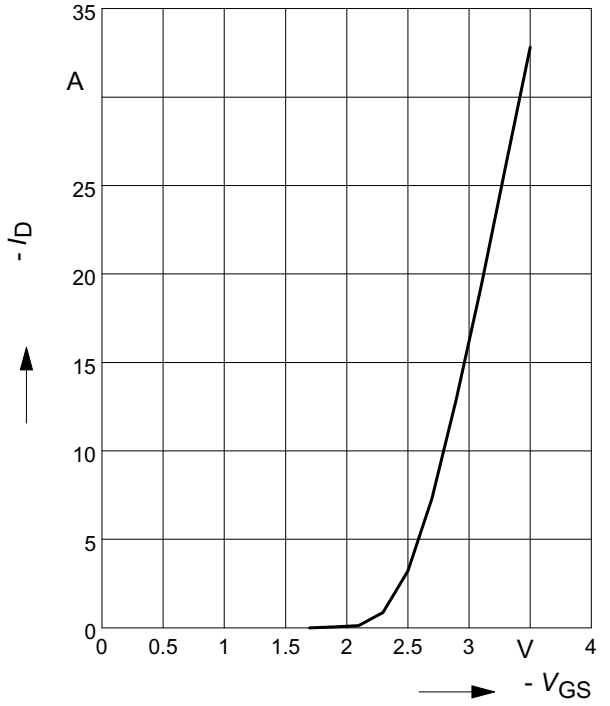
parameter: V_{GS}



7 Typ. transfer characteristics

$I_D = f(V_{GS})$; $|V_{DS}| \geq 2 \times |I_D| \times R_{DS(on)max}$

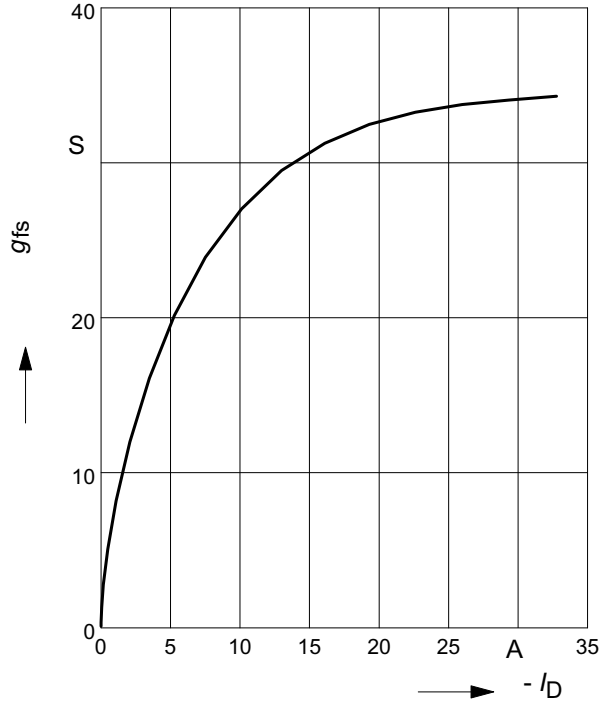
parameter: t_p = 80 µs



8 Typ. forward transconductance

g_{fs} = f(I_D); T_j=25°C

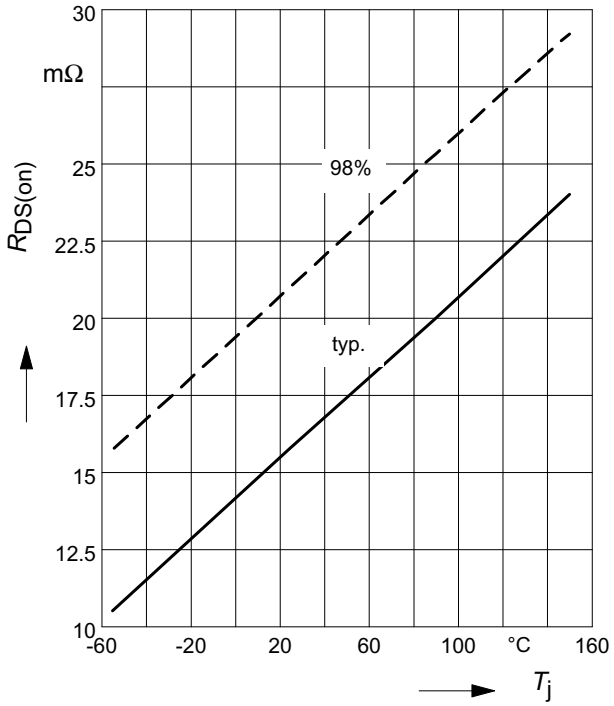
parameter: t_p = 80 µs



9 Drain-source on-resistance

$R_{DS(on)} = f(T_j)$

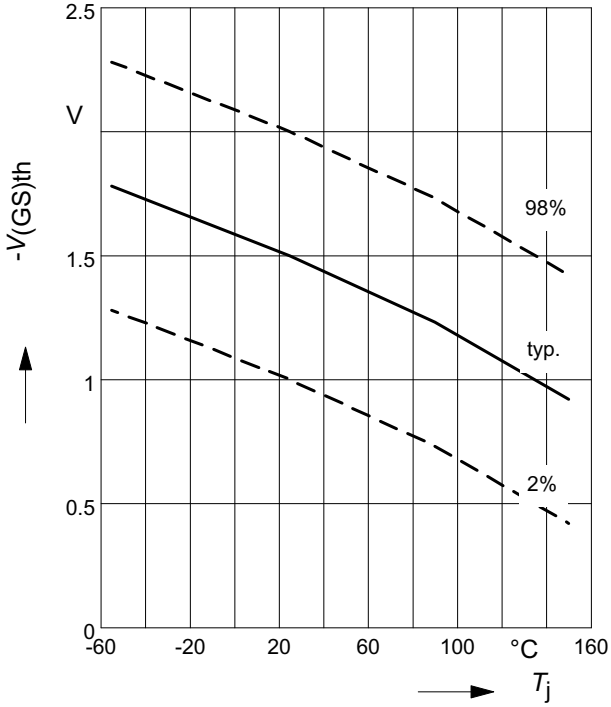
parameter: I_D = -8.2 A, V_{GS} = -10 V



10 Typ. gate threshold voltage

$V_{GS(th)} = f(T_j)$

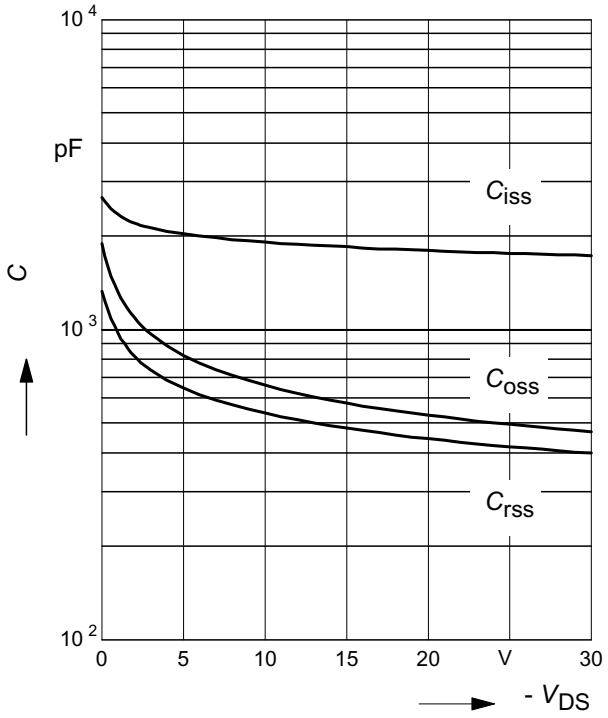
parameter: $V_{GS} = V_{DS}$



11 Typ. capacitances

$C = f(V_{DS})$

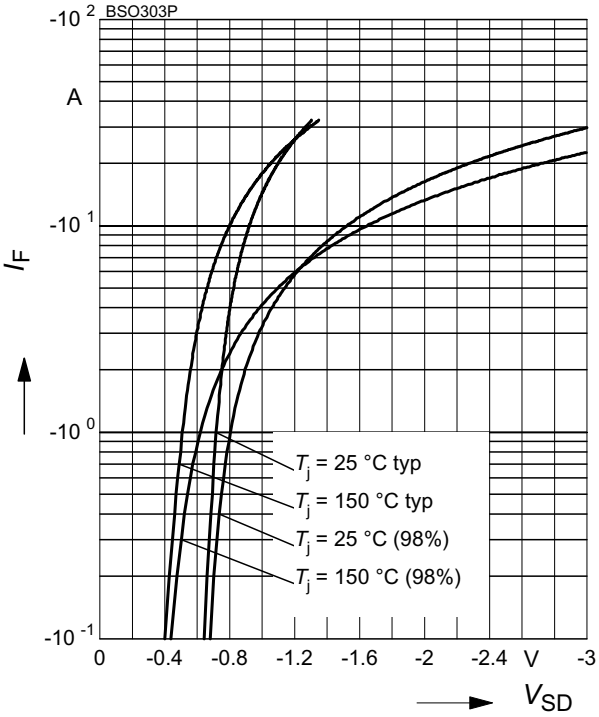
parameter: V_{GS}=0, f=1 MHz



12 Forward character. of reverse diode

$I_F = f(V_{SD})$

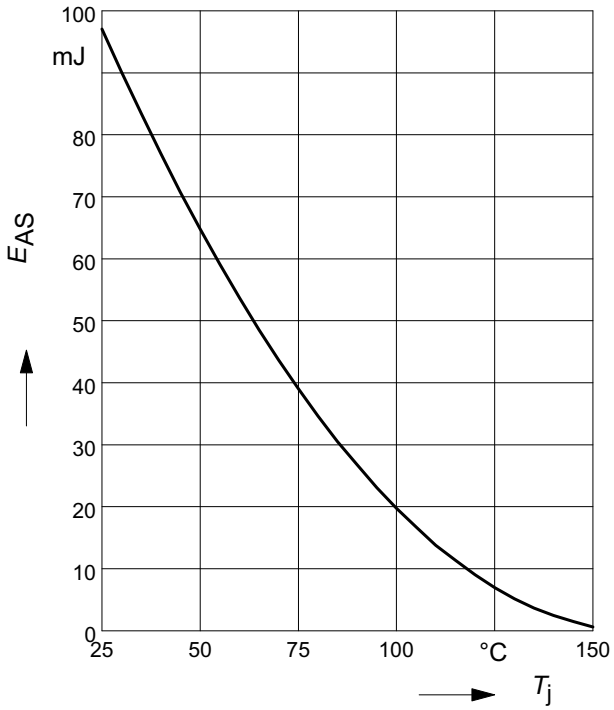
parameter: T_j , tp = 80 µs



13 Typ. avalanche energy

$E_{AS} = f(T_j)$, par.: I_D = -8.2 A

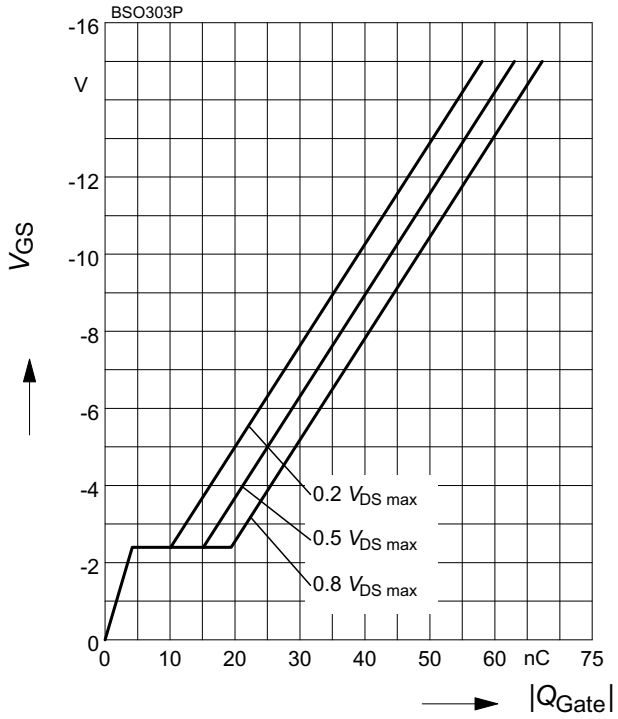
V_{DD} = -25 V, R_{GS} = 25 Ω



14 Typ. gate charge

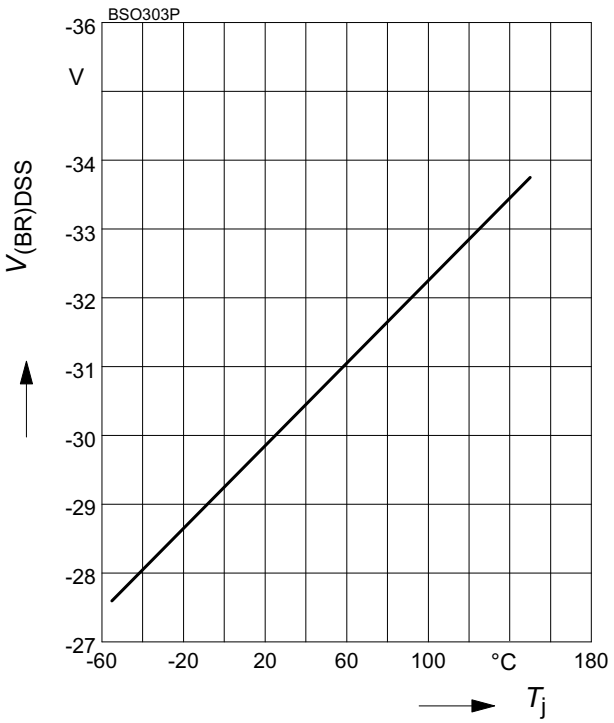
$V_{GS} = f\ (Q_{Gate})$

parameter: I_D = -8.2 A pulsed



15 Drain-source breakdown voltage

$V_{(BR)DSS} = f(T_j)$



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